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PATENT

Docket No.: NAU-058

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECORDING COVER SHEET

1. Assignor: Jui-Tsen Huang, Kuang-Hua Shih
Tsu-An Lin, Chan-Lon Yang
2. Assignee: UNITED MICROELECTRONICS CORP.
No.3, Li-Hsin Road 2,
Science-Based Industrial Park,
Hsin-Chu, Taiwan, R.O.C.
3. Nature of Conveyance: Assignment of patent
4. Reference number: Application filed herewith.
5. Correspondence to: Winston Hsu
3F, No. 52, Lane 46, Min-Sheng Rd.,
Yung-Ho City, Taipei Hsien,
Taiwan, R.O.C.
6. Number of applications affected by this recording: 1
Total fee: (1 x \$ 40) = \$ 40.00 Payment by check enclosed
Authorization is hereby given to charge the over payment to deposit account #500801
7. Execution date of the document to be recorded: 06/15 /1999
8. Total number of pages including cover sheet: 3
9. I declare under penalty of perjury that to the best of my knowledge and belief, the information contained on this cover sheet is true and correct, and that any copy submitted herewith is a true and correct copy of the original document.



07/08/1999 KHR/LIN 00000038 09340400

02 FC:581

Date: 07/22/1999
40.00 CP

Winston Hsu

Winston Hsu
U.S. Patent Agent
Reg. No.:41,526

PATENT

REEL: 010073 FRAME: 0735

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNORS (Inventors):

Name: Jui-Tsen Huang Nationality: R.O.C.

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Name: Kuang-Hua Shih Nationality: R.O.C.

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Name: Chan-Lon Yang Nationality: R.O.C.

Address: 4F, No.7, Lane 100, Kuang-Fu N. Rd., Taipei City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **UNITED MICROELECTRONICS CORP.**
(hereinafter "Assignee"), of (Assignee address) **No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.**, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:
" Method for etching a poly-silicon layer of a semiconductor wafer "

Which is found in :

- (a) _____ U.S. patent application executed on even date herewith
 (b) _____ U.S. patent application executed on _____
 (c) _____ U.S. application serial no. _____
 (d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 06/15/99 (Date of signing).

(Type name of inventor)

Signature of INVENTOR

Jui-Tsen Huang

Jui-Tsen Huang 6/15/99

Kuang-Hua Shih

Kuang-Hua Shih

Tsu-An Lin

Tsu-An Lin

Chan-Lon Yang

Chan-Lon Yang